REAL TIME CLOCK MODULE (SPI-Bus)

High-Stability Frequency with Built in Timestamp and **Power Switching**

RX-4035 SA/LC

•Built-in 32.768 kHz crystal unit : Frequency adjusted for high accuracy. $\begin{array}{c} (\pm\,5\times10^{-6}\,/\,T_a=+25\,^{\circ}C) \\ \text{•Interface Type} \end{array} : \begin{array}{c} \text{SPI-Bus}\,(1\text{MHz}) \end{array}$

 Interface Type
 Operating voltage range
 Timekeeping voltage range
 Low backup current
 Time detections. •Interface type
•Operating voltage range
•Operating voltage range
•Timekeeping voltage range
•Low backup current
•Event detection and Time stamp
•Dual event detection ports
•Auto power switching functions
•Very content of the property of

•Auto power switching functions

internal source is switched to VBAT.



Product Number (Please contact us) RX-4035SA: X1B000192xxxx00 RX-4035LC: X1B000202xxxx00





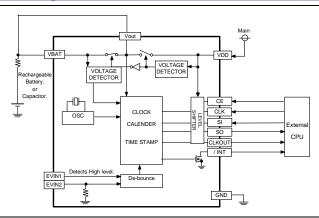
Actual size

RX-4035SA RX-4035LC





Block diagram



Overview

The event detection and Timestamp function

Dual event detection terminals Selectable de-bounce period 35ms or 2s. Available event detection interrupt output.

· Power switching functions.

- When VDD is less than 2.4V, an internal source is switched
- Note: When the supply from VBAT, SPI interface are

Alarm, Periodic interrupt, 32.768kHz clock output.

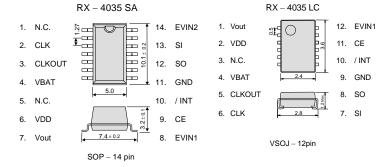
- Available monthly-alarm and weekly-alarm.
- •Interrupt period are selectable from 2Hz to Monthly.
- •CLKOUT outputs 32.768kHz clock powered by VDD.

Pin function

Signal Name	Input / Output	Function	
VBAT	-	Power supply for backup.	
Vout	Output	Switched power out. (maximum output current 20mA)	
CE	Input	SPI chip enable.	
CLK	Input	SPI serial clock.	
SO	Output	SPI data out.	
SI	Input	SPI data in.	
GND	_	Ground	
EVIN1	Input	Event detection input 1	
EVIN2	Input	Event detection input 2	
/ INT	Output	Interrupt out.	
CLKOUT	Output	32.768kHz output. (CMOS. Can not inhibit.)	
N.C.	_	Do not connect.	
VDD	_	Main power supply.	

Terminal connection / External dimensions

(Unit:mm)



The metal case inside of the molding compound may be exposed on the top or bottom of this product. This purely cosmetic and does not have any effect on quality, reliability or electrical specs.

Any glue must never use it after soldering LC-package to a circuit board. This product has glass on the back side of a package. When glue invasions between circuit board side and glass side, then glass cracks by thermal expansion of glue. In this case a crystal oscillation stops. Consider glue abolition or glue do not touch to LC-package

Specifications (characteristics)

Recommended Operating Conditions

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Operating voltage	VACCESS	VDD	2.4	3.0	5.5	V
Time keeping voltage	Vclk	VBAT	1.0	3.0	5.5	V
Operating temperature	Topr	_	-40	+25	+85	°C
Storage temperature	Tstg	_	-55	_	+125	°C

Frequency characteristics

Item	Symbol	Conditions	Rating	Unit
Frequency tolerance	Δf/f	Ta = +25°C VBAT = 3.0 V	B: 5 ± 23 *1) AA: 5 ± 5 *2) AC: 0 ± 5 *2)	× 10 ⁻⁶
Oscillation start-up time	t sta	Ta = +25 °C VDD = 3.0 V	1 Max.	s
Frequency / voltage characteristics	f/V	Ta = +25 °C VDD = 2.4 V to 5.5 V	± 1 Max.	× 10 ⁻⁶

Equivalent to 1 minute of monthly deviation (excluding offset.) *1) Equivalent to 1 minute of monthly deviation (excluding offset.)
*2) Equivalent to 13 seconds of monthly deviation (excluding offset.)

* Refer to application manual for details.

Current consumption characteristics

CE = 0VCLKOUT = open

Symb

IBA*

IDD

Current Consumption

sur	mption characteristics		Ta = -40 °C to +85 °C			
bol	Conditions	Min.	Тур.	Max.	Unit	
т	RX-4035SA VBAT = 3.0V, VDD = 0.0V CE = 0V, CLKOUT = open	-	350	1200	nA	
Т	RX-4035LC VBAT = 3.0V, VDD = 0.0V CE = 0V, CLKOUT = open		400			
	VDD = 3.0V					

1.40

2.50

Power supply detection voltage					$T_a = -40 ^{\circ}\text{C} \text{ to } +85 ^{\circ}\text{C}$			
Item	Symbol	Conditions	Min.	Тур.	Max.	Unit		
BAT detect voltage	VLOW		1.10	1.25	1.40	V		
ower switching voltage VDD to VBAT)	V _{D2B}	+25 °C	2.328	2.40	2.472	V		
•		<u> </u>						

PROMOTION OF ENVIRONMENTAL MANAGEMENT SYSTEM CONFORMING TO INTERNATIONAL STANDARDS

At Seiko Epson, all environmental initiatives operate under the Plan-Do-Check-Action (PDCA) cycle designed to achieve continuous improvements. The environmental management system (EMS) operates under the ISO 14001 environmental management standard.

All of our major manufacturing and non-manufacturing sites, in Japan and overseas, completed the acquisition of ISO 14001 certification.

ISO 14000 is an international standard for environmental management that was established by the International Standards Organization in 1996 against the background of growing concern regarding global warming, destruction of the ozone layer, and global deforestation.

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ISO/TS16949 is the international standard that added the sector-specific supplemental requirements for automotive industry based on ISO9001.

Explanation of the mark that are using it for the catalog



►Pb free.



- ► Complies with EU RoHS directive.
 - *About the products without the Pb-free mark.

 Contains Pb in products exempted by EU RoHS directive.

 (Contains Pb in sealing glass, high melting temperature type solder or other.)



▶ Designed for automotive applications such as Car Multimedia, Body Electronics, Remote Keyless Entry etc.



 \blacktriangleright Designed for automotive applications related to driving safety (Engine Control Unit, Air Bag, ESC etc).

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